

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (original) An electronic component package comprising:
a substrate comprising:
a first surface;
a second surface;
a side; and
a ground shield extending from said first surface to said second surface and adjacent said side; and
an electronic component coupled to said first surface.
2. (original) The electronic component package of Claim 1 wherein said ground shield comprises a plurality of electrically conductive ground vias.
3. (currently amended) The electronic component package of Claim 2 wherein said ground vias are spaced sufficiently close to one another to prevent radiation from passing between said ground vias.
4. (original) The electronic component package of Claim 1 wherein said ground shield extends around a periphery of said substrate.
5. (original) The electronic component package of Claim 1 further comprising a shield ring coupled to said first surface of said substrate, said shield ring defining a central region of said first surface of said substrate, said electronic component being coupled to said central region.
6. (original) The electronic component package of Claim 5 wherein said shield ring comprises upper ground traces.

7. (original) The electronic component package of Claim 6 wherein said upper ground traces are adjacent said side of said substrate.

8. (original) The electronic component package of Claim 6 further comprising a shield electrically coupled to said shield ring, said shield enclosing said electronic component.

9. (original) The electronic component package of Claim 8 wherein said shield comprises a shield connection surface, said electronic component package further comprising an electrically conductive adhesive coupling said shield connection surface to said shield ring.

10. (original) An electronic component package comprising:

a substrate comprising a first surface comprising a central region defined by a shield ring;

a shield electrically coupled to said shield ring, said shield being continuous; and

an electronic component coupled to said central region.

11. (original) The electronic component package of Claim 10 wherein said shield comprises a shield connection surface, said shield ring corresponding in shape to said shield connection surface.

12. (original) The electronic component package of Claim 11 wherein said shield connection surface comprises a rectangular annulus.

13-23.. (canceled)

24. (original) An electronic component package comprising:

a substrate comprising a first surface;
a first shield ring defining a first central region of said first surface of said substrate;
a second shield ring defining a second central region of said first surface of said substrate;
a first electronic component coupled to said first central region;
a second electronic component coupled to said second central region;
a first shield enclosing said first electronic component, said first shield being electrically coupled to said first shield ring; and
a second shield enclosing said second electronic component, said second shield being electrically coupled to said second shield ring.

25. (original) The electronic component package of Claim 24 wherein said first electronic component is shielded from said second electronic component by said first shield and said second shield.

26. (original) The electronic component package of Claim 24 wherein said first shield is grounded separately from said second shield.

27. (original) The electronic component package of Claim 24 wherein said first shield and said second shield are commonly grounded.

28. (original) The electronic component package of Claim 27 wherein said first shield is electrically coupled to said second shield.

29. (original) The electronic component package of Claim 24 wherein said first shield ring and said second shield ring share a common side.

30. (canceled)

31. (original) A method comprising:

forming a shield ring on a first surface of a substrate,
said shield ring defining a central region of said first
surface;

coupling an electronic component to said central region;

forming a dielectric cap;

coupling a shield to said dielectric cap; and

coupling said shield to said shield ring.

32. (original) The method of Claim 31 wherein said
forming a shield ring comprises forming upper ground traces on
said first surface of said substrate.

33. (original) The method of Claim 31 wherein said
electronic component is coupled to said central region in a
wirebond configuration.

34. (original) The method of Claim 31 when the
electronic component is coupled to said central region in a
flip chip configuration.

35. (original) The method of Claim 31 wherein said
dielectric cap is formed by a plastic injection molding.

36. (original) The method of Claim 31 wherein said
shield is coupled to said dielectric cap by an adhesive.

37. (original) The method of Claim 31 wherein said
shield is coupled to said dielectric cap by heat staking.

38. (original) The method of Claim 31 wherein said
coupling a shield to said dielectric cap comprises sputtering
an electrically conductive material on said dielectric cap.

39. (original) The method of Claim 31 wherein said shield is coupled to said shield ring by an electrically conductive adhesive.

40. (original) A method comprising:

forming a shield ring on a first surface of a substrate, said shield ring defining a central region of said first surface;

forming an antenna trace on said first surface of said substrate;

coupling an electronic component to said central region;

forming a dielectric cap;

coupling a shield to said dielectric cap;

coupling an antenna to said dielectric cap;

coupling said shield to said shield ring; and

coupling said antenna to said antenna trace.

41. (original) The method of Claim 40 further comprising shielding said electronic component from radiation with said shield.

42. (original) The method of Claim 41 wherein said shield is a ground plane for said antenna.